- ANSWER 1 OF 12 CAPLUS COPYRIGHT 2008 ACS on STN L3
- ΑN 2008:739313 CAPLUS
- 149:91973 DN
- Cyclic chemical vapor deposition of metal-silicon containing films TΙ
- Lei, Xinjian; Thridandam, Hareesh; Xiao, Manchao; Bowen, Heather Regina; ΙN Gaffney, Thomas Richard
- PAAir Products and Chemicals, Inc., USA
- SO U.S. Pat. Appl. Publ., 5pp. CODEN: USXXCO
- DT Patent
- English LA
- FAN.CNT 1

L MIA .	∠1/I T	_																
	PATENT NO.					KIND		DATE			APPLICATION NO.					DATE		
							_											
ΡI	US 20080145535			A1		20080619			US 2007-949868				20071204					
	KR 2008055689					A 2008061			0619	KR 2007-129800					20071213			
	EΡ	EP 1939323				A1		20080702			EP 2007-123150				20071213			
		R:	ΑT,	BE,	BG,	CH,	CY,	CZ,	DE,	DK,	EE,	ES,	FΙ,	FR,	GB,	GR,	HU,	ΙE,
			IS,	ΙΤ,	LI,	LT,	LU,	LV,	MC,	MT,	ΝL,	PL,	PT,	RO,	SE,	SI,	SK,	TR,
			ΑL,	BA,	HR,	MK,	RS											
	CN 101220465			А	A 20080716			CN 2007-10300368						20071213				
PRAI	US	2006	-874	653P		P		2006	1213									
	US	2007	-9498	868		Α		2007	1204									

- ANSWER 2 OF 12 CAPLUS COPYRIGHT 2008 ACS on STN L3
- 2007:621154 CAPLUS ΑN
- 147:43828 DN
- ΤI Method of manufacturing semiconductor device having tungsten carbon nitride layer
- Jeon, Taek-Soo; Cho, Hag-Ju; Lee, Hye-Lan; Shin, Yu-Gyun; Kang, Sang-Bom ΙN
- PΑ Samsung Electronics Co., Ltd., S. Korea
- SO U.S. Pat. Appl. Publ., 19pp. CODEN: USXXCO
- DT Patent
- English LA
- FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE		
ΡI	US 20070128775	A1	20070607	US 2006-607600	20061201		
	KR 666917	В1	20070110	KR 2005-116754	20051202		
PRAI	KR 2005-116754	А	20051202				

- L3 ANSWER 3 OF 12 CAPLUS COPYRIGHT 2008 ACS on STN
- ΑN 2007:546662 CAPLUS
- 147:17560 DN
- ΤI The role of ammonia in atomic layer deposition of tungsten nitride
- Mukhopadhyay, Atashi B.; Musgrave, Charles B. ΑU
- Department of Chemical Engineering, Stanford University, Stanford, CA, CS 94305, USA
- Applied Physics Letters (2007), 90(17), 173120/1-173120/3 SO CODEN: APPLAB; ISSN: 0003-6951
- PΒ American Institute of Physics
- DT Journal
- LA English
- RE.CNT 16 THERE ARE 16 CITED REFERENCES AVAILABLE FOR THIS RECORD ALL CITATIONS AVAILABLE IN THE RE FORMAT
- ANSWER 4 OF 12 CAPLUS COPYRIGHT 2008 ACS on STN L3
- ΑN 2007:485655 CAPLUS
- DN 146:473503
- TΙ Film-forming method and film-forming apparatus

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PΑ
    Tokyo Electron Limited, Japan
    PCT Int. Appl., 48pp.
SO
    CODEN: PIXXD2
DT
    Patent
LA
    Japanese
FAN.CNT 1
    WO 2007049612 A1 000
    PATENT NO.
                      KIND DATE
                                     APPLICATION NO.
                                       _____
                       A1 20070503 WO 2006-JP321156 20061024
        W: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH,
            CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD,
            GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, KE, KG, KM, KN, KP,
            KR, KZ, LA, LC, LK, LR, LS, LT, LU, LV, LY, MA, MD, MG, MK, MN,
            MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RS,
            RU, SC, SD, SE, SG, SK, SL, SM, SV, SY, TJ, TM, TN, TR, TT, TZ,
            UA, UG, US, UZ, VC, VN, ZA, ZM, ZW
        RW: AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE,
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            CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG, BW, GH,
            GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW, AM, AZ, BY,
            KG, KZ, MD, RU, TJ, TM
                              20070510
                                         JP 2005-308817
    JP 2007113103 A
                                                                20051024
                       Α
    KR 2008023741
                              20080314
                                         KR 2008-701229
                                                                20080116
                           20051024
PRAI JP 2005-308817
                       Α
    WO 2006-JP321156
                        W
                              20061024
             THERE ARE 9 CITED REFERENCES AVAILABLE FOR THIS RECORD
RE.CNT 9
             ALL CITATIONS AVAILABLE IN THE RE FORMAT
    ANSWER 5 OF 12 CAPLUS COPYRIGHT 2008 ACS on STN
L3
    2007:405366 CAPLUS
ΑN
    146:413700
DN
ΤI
    Ti, Ta, Hf, Zr and related metal amidosilanes for ALD/CVD of metal-silicon
    nitrides, oxides, oxides or oxynitrides
IN
    Norman, John Antony Thomas; Lei, Xinjian
PA
    Air Products and Chemicals, Inc., USA
SO
    Eur. Pat. Appl., 17pp.
    CODEN: EPXXDW
\mathsf{DT}
    Patent
   English
LA
FAN.CNT 1
    PATENT NO.
                 KIND DATE APPLICATION NO. DATE
    EP 1772460 A1 20070411 EP 2006-255104 20061003
PΤ
        R: AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE,
            IS, IT, LI, LT, LU, LV, MC, NL, PL, PT, RO, SE, SI, SK, TR, AL,
            BA, HR, MK, YU
    US 20070082500
                              20070412
                                         US 2006-522768
                       A1
                                                                20060918
                       Α
    CN 1990492
                             20070704
                                         CN 2006-10144437
                                                               20060930
                            20070411
    кк 2007038914
JP 2007131616
                       A
A
                                        KR 2006-97693
                                                               20061004
                             20070531
                                         JP 2006-275057
                                                                20061006
                       P
PRAI US 2005-724757P
                              20051007
    US 2006-522768
                       Α
                              20060918
    MARPAT 146:413700
             THERE ARE 6 CITED REFERENCES AVAILABLE FOR THIS RECORD
             ALL CITATIONS AVAILABLE IN THE RE FORMAT
L3
    ANSWER 6 OF 12 CAPLUS COPYRIGHT 2008 ACS on STN
ΑN
    2007:53943 CAPLUS
DN
    146:153750
ΤI
    Method of forming film and apparatus for film formation
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TN

Yamasaki, Hideaki; Kawano, Yumiko

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PΑ
     Tokyo Electron Limited, Japan
     PCT Int. Appl., 44pp.
SO
     CODEN: PIXXD2
DT
     Patent
LA
     Japanese
FAN.CNT 1
                                         APPLICATION NO.
     PATENT NO.
                        KIND DATE
     W: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH,
             CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD,
             GE, GH, GM, HN, HR, HU, ID, IL, IN, IS, KE, KG, KM, KN, KP, KR,
             KZ, LA, LC, LK, LR, LS, LT, LU, LV, LY, MA, MD, MG, MK, MN, MW,
             MX, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RS, RU, SC,
             SD, SE, SG, SK, SL, SM, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US,
             UZ, VC, VN, ZA, ZM, ZW
         RW: AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE,
             IS, IT, LT, LU, LV, MC, NL, PL, PT, RO, SE, SI, SK, TR, BF, BJ,
             CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG, BW, GH,
             GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW, AM, AZ, BY,
             KG, KZ, MD, RU, TJ, TM
                                           JP 2006-185655
EP 2006-768005
                              20070215
20080507
     JP 2007039806 A
                                                                      20060705
     EP 1918417
                          Α1
                                                                      20060707
         R: AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LI, LT, LU, LV, MC, NL, PL, PT, RO, SE, SI, SK, TR
     CN 101128620 A 20080220 CN 2006-80006297 20070828
RR 2007100391 A 20071010
PRAI JP 2005-199281 A 20050707
JP 2006-185655 A 20060705
WO 2006-JP313595 W 20060707
                                            KR 2007-719763
                                                                      20070829
RE.CNT 5 THERE ARE 5 CITED REFERENCES AVAILABLE FOR THIS RECORD
              ALL CITATIONS AVAILABLE IN THE RE FORMAT
     ANSWER 7 OF 12 CAPLUS COPYRIGHT 2008 ACS on STN
L3
ΑN
     2006:818014 CAPLUS
DN
     145:239565
     Preparation of metal silicon nitride films via cyclic deposition
TΙ
     Lei, Xinjian; Thridandam, Hareesh; Cuthill, Kirk Scott; Hochberg, Arthur
     Kenneth
PA
     Air Products and Chemicals, Inc., USA
     Eur. Pat. Appl., 16pp.
SO
     CODEN: EPXXDW
DT
     Patent
LA
     English
FAN.CNT 1
                        KIND DATE APPLICATION NO. DATE
     PATENT NO.
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                         A1 20060816 EP 2006-2371
     EP 1691400
PΙ
         R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, LT, LV, FI, RO, MK, CY, AL, TR, BG, CZ, EE, HU, PL, SK,
             BA, HR, IS, YU
                      A1
     US 20060182885
                                 20060817
                                              US 2005-57446
                                                                      20050214
                          В
     TW 265207 B 20061101
KR 2006091240 A 20060818
KR 766843 B1 20071017
CN 1821440 A 20060823
JP 2006225764 A 20060831
US 2005-57446 A 20050214
     TW 265207
                                 20061101
                                              TW 2006-95104258
                                                                      20060208
                                              KR 2006-12812
                                                                      20060210
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                                             JP 2006-36223
                                                                      20060214
PRAI US 2005-57446
              THERE ARE 7 CITED REFERENCES AVAILABLE FOR THIS RECORD
RE.CNT 7
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ALL CITATIONS AVAILABLE IN THE RE FORMAT

Nakamura, Kazuhito; Yamasaki, Hideaki; Kawano, Yumiko

TN

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ANSWER 8 OF 12 CAPLUS COPYRIGHT 2008 ACS on STN
L3
     2004:60731 CAPLUS
ΑN
DN
     140:120241
ΤI
     Vapor deposition of tungsten nitride
     Gordon, Roy G.; Suh, Seigi; Becker, Jill
IN
PA
     President and Fellows of Harvard College, USA
SO
     PCT Int. Appl., 37 pp.
     CODEN: PIXXD2
     Patent
DT
     English
LA
FAN.CNT 1
     PATENT NO.
                         KIND DATE
                                          APPLICATION NO.
                                                                      DATE
                         ____
                                               _____
     WO 2004007796
                          A1 20040122 WO 2003-US21281
PΙ
                                                                       20030709
         W: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN,
              CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH,
             GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, OM, PH,
              PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, TJ, TM, TN, TR, TT, TZ,
              UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW
         RW: GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW, AM, AZ, BY, KG, KZ, MD, RU, TJ, TM, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR, BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG
                                            AU 2003-248850
                                                                     20030709
     AU 2003248850
                                  20040202
                           Α1
     EP 1543177
                           Α1
                                  20050622
                                              EP 2003-764377
                                                                        20030709
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              IE, SI, LT, LV, FI, RO, MK, CY, AL, TR, BG, CZ, EE, HU, SK
                               20050928 CN 2003-819074 20030709
                          A
     CN 1675402
     JP 2005533178
                           Т
                                  20051104
                                               JP 2004-521556
                                                                        20030709
     US 20060125099
                                              US 2005-520456
                                                                        20051019
                          A1 20060615
                          P
PRAI US 2002-395572P
                                  20020712
                           W
     WO 2003-US21281
                                  20030709
     MARPAT 140:120241
OS
RE.CNT 8
               THERE ARE 8 CITED REFERENCES AVAILABLE FOR THIS RECORD
               ALL CITATIONS AVAILABLE IN THE RE FORMAT
L3
     ANSWER 9 OF 12 CAPLUS COPYRIGHT 2008 ACS on STN
     2003:727571 CAPLUS
ΑN
DN
     139:356711
ΤI
     Characteristics of tungsten carbide films prepared by plasma-assisted ALD
     using bis(tert-butylimido)bis(dimethylamido)tungsten
ΑIJ
     Kim, Do-Heyoung; Kim, Young Jae; Song, Yo Soon; Lee, Byung-Teak; Kim, Jin
     Hyeok; Suh, Seigi; Gordon, Roy
     Faculty of Applied Chemical Engineering and Research Institute for
CS
     Catalysis, Thin Film Laboratory, Chonnam National University, KwangJu,
     500-757, S. Korea
     Journal of the Electrochemical Society (2003), 150(10), C740-C744
SO
     CODEN: JESOAN; ISSN: 0013-4651
PΒ
     Electrochemical Society
DT
     Journal
     English
RE.CNT 23
               THERE ARE 23 CITED REFERENCES AVAILABLE FOR THIS RECORD
               ALL CITATIONS AVAILABLE IN THE RE FORMAT
     ANSWER 10 OF 12 CAPLUS COPYRIGHT 2008 ACS on STN
L3
ΑN
     2003:473448 CAPLUS
DN
     139:189002
ΤI
     Highly Conformal Thin Films of Tungsten Nitride Prepared by Atomic Layer
```

Deposition from a Novel Precursor

- AU Becker, Jill S.; Suh, Seigi; Wang, Shenglong; Gordon, Roy G.
- CS Department of Chemistry and Chemical Biology, Harvard University, Cambridge, MA, 02138, USA
- SO Chemistry of Materials (2003), 15(15), 2969-2976 CODEN: CMATEX; ISSN: 0897-4756
- PB American Chemical Society
- DT Journal
- LA English
- RE.CNT 27 THERE ARE 27 CITED REFERENCES AVAILABLE FOR THIS RECORD ALL CITATIONS AVAILABLE IN THE RE FORMAT
- L3 ANSWER 11 OF 12 CAPLUS COPYRIGHT 2008 ACS on STN
- AN 2003:267659 CAPLUS
- DN 139:44679
- TI Diffusion barrier properties of tungsten nitride films grown by atomic layer deposition from bis(tert-butylimido)bis(dimethylamido)tungsten and ammonia
- AU Becker, Jill S.; Gordon, Roy G.
- CS Department of Chemistry and Chemical Biology, Harvard University, Cambridge, MA, 02138, USA
- SO Applied Physics Letters (2003), 82(14), 2239-2241 CODEN: APPLAB; ISSN: 0003-6951
- PB American Institute of Physics
- DT Journal
- LA English
- RE.CNT 9 THERE ARE 9 CITED REFERENCES AVAILABLE FOR THIS RECORD ALL CITATIONS AVAILABLE IN THE RE FORMAT
- L3 ANSWER 12 OF 12 CAPLUS COPYRIGHT 2008 ACS on STN
- AN 2002:256544 CAPLUS
- DN 136:286888
- ${
 m TI}$ Vapor deposition of metal oxides, silicates and phosphates, and silicon dioxide
- IN Gordon, Roy G.; Becker, Jill; Hausmann, Dennis; Suh, Seigi
- PA President and Fellows of Harvard College, USA
- SO PCT Int. Appl., 51 pp. CODEN: PIXXD2
- DT Patent
- LA English
- FAN.CNT 1

	PATENT NO.			KIND DATE			APPLICATION NO.											
PI	WO	2002 2002	0270 0270	63		A2		2002 2002	0404			2001-					0010	
			AT,	•	CH,	CY,	DE,	DK,	ES,	FI,	FR,	GB,	GR,	IE,	IT,	LU,	MC,	NL,
	EP 1327010			A2 20030716			EP 2001-975576						20010928					
		R:	ΑT,	BE,	CH,	DE,	DK,	ES,	FR,	GB,	GR,	ΙT,	LI,	LU,	NL,	SE,	MC,	PT,
			ΙE,	FΙ,	CY,	TR												
	JΡ	2004	5276	51		T		2004	0909		JP 2	2002-	5308:	23		2	0010	928
	EP	1772	534			A2		2007	0411		EP 2	2006-	2627	7		2	0010	928
	EP	EP 1772534				A3 20070425												
		R:	ΑT,	BE,	CH,	CY,	DE,	DK,	ES,	FI,	FR,	GB,	GR,	ΙE,	ΙΤ,	LI,	LU,	MC,
			NL,	PT,	SE,	TR												
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	US	2004	0043	149		A1		2004	0304		US 2	2003-	3816:	28		2	0030	902
	US	6969	539			В2		2005	1129									
		2005						2005	1215		US 2	2005-	1990	32		2	0050	808
	KR	2007						2007	1107		KR 2	2007-	7240	96		2	0071	019
	KR	8149	80			В1		2008	0318									

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	US	2000-253917P	P	20001129
	EΡ	2001-975576	А3	20010928
	WO	2001-US30507	W	20010928
	KR	2003-704494	А3	20030328
	US	2003-381628	A1	20030902
OS	MAI	RPAT 136:286888		